

**100% Material Declaration Data Sheet:
FGG484****Average Weight: 1.95g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (Grams)	Component Percent of Total
Silicon Die					0.049	2.54%
	Silicon	7440-21-3	100.00		0.049	
Die Attach Material					0.0079	0.41%
	Polymetric Resin	Trade Secret	3.00		0.0002	
	Diester Resin	Trade Secret	20.00		0.0015	
	Acrylate Resin	Trade Secret	7.00		0.0006	
	Silver	7440-22-4	70.00		0.0056	
Mold Compound					0.00175	0.09%
	SiO2 Filler	60676-86-0	86.20	Filler	0.00151	
	Epoxy Resin A	Trade Secret	3.00		0.00005	
	Epoxy Resin B	Trade Secret	3.00		0.00005	
	Phenol Resin A	Trade Secret	3.00		0.00005	
	Phenol Resin B	Trade Secret	3.00		0.00005	
	Metal Hydroxide	Trade Secret	1.50		0.00003	
	Carbon Black	1333-86-4	0.30		0.00001	
Substrate					1.4707	75.42%
	Copper	7440-50-8	46.27	Metal Layer	0.6805	
	Nickel	7440-02-0	0.60	Metal Layer	0.0088	
	Gold	7440-57-5	0.13	Metal Layer	0.0019	
	Glass Fiber (GF)	N/A	23.00		0.3383	
	Halogen Fire Retardant	N/A	3.20		0.0471	
	BT (core)	N/A	16.80		0.2471	
	Solder Mask (EP)	N/A	10.00		0.1470	
Gold Wire					0.01587	0.81%
	Gold	74410-57-5	100.00		0.01587	
Solder Balls					0.4043	20.73%
	Tin	7440-31-5	95.50		0.3861	
	Silver	7440-22-4	4.00		0.0162	
	Copper	7440-50-8	0.50		0.0020	

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
03/21/08	1.0	Initial Xilinx release.
05/15/06	1.1	100 percent material declaration.
09/18/06	1.2	Updated component descriptions.
01/08/07	1.2.1	Corrected Gold Wire CAS number entry.
05/30/08	1.3	Correct CAS number for silver in solder ball composition. Updated weights.
12/12/08	1.3.1	Tech Pubs' edit.

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